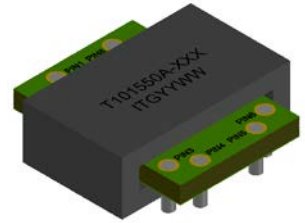


1. Features of T101550A Series:

- SMD planar transformer with full selection of turn ratios.
- Primary current rating of 26 to 35A for T101550A.
- Inductance range from 1.5 μ H to 6.0 μ H. Custom values are welcomed.
- 25.5 x 25.3 mm Max. Foot Print with 9.00 mm Max. height.
- Hi-Pot rating of 200 Vrms for T101550A.
- Tape & Reel Quantity: 200 pieces per 13 inches reel.
- RoHS and HF compliant.

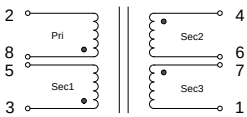


2. Electrical Characteristics of T101550 Series:

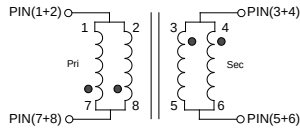
ITG Part Number	DCR (m Ω Max.)		Inductance @250KHz/0.1V (μ H Min.)	Leakage Inductance @250KHz/0.1V (nH Typ.)	Primarily rated (A)	Hi-Pot Pri to Sec (V _{AC})	Turns Ratio Pri : Sec
	Primary	Secondary					
T101550A-004	1.0	1.0	1.5	15	35	200	1:1:1:1
T101550A-005	0.6	0.6	1.5	15	30	200	1:1
T101550A-006	2.2	2.2	6.0	55	26	200	2:2
T101550A-007	2.2	1.0	6.0	65	35	200	2:1:1

3. Mechanical Dimension of T101550 Series (UNIT:mm):

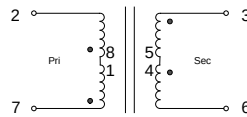
Dimension	A Max.	B Max.	C Max.	E1 ± 0.5	E1 ± 0.3	E1 ± 0.5	E1 ± 0.5	F ± 0.10	G ± 0.20
T101550A Series	25.5	25.3	9.0	14.3	8.3	21.3	17.9	1.7	3.0



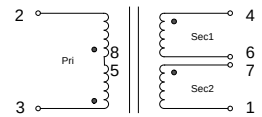
Pri:Sec1:Sec2:Sec3=1:1:1:1
Schematic:T101550A-004



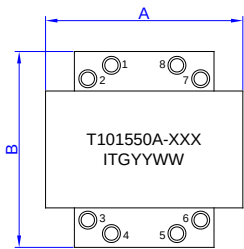
Pri:Sec=1:1
Schematic:T101550A-005



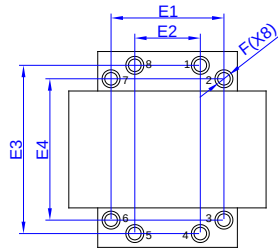
Pri:Sec=2:2
Schematic:T101550A-006



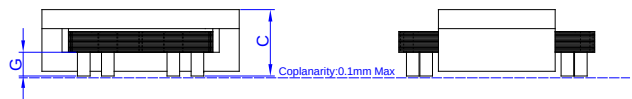
Pri:Sec1:Sec2:Sec3=1:1:1:1
Schematic:T101550A-007



Top View

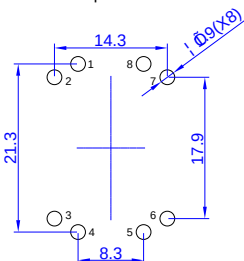


Bottom View

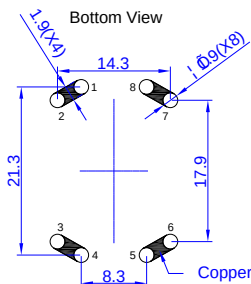


Front View

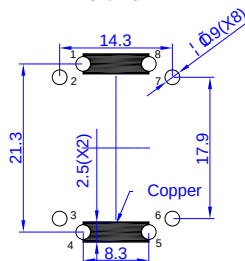
Side View



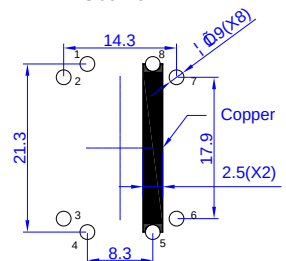
T101550A-004



T101550A-005



T101550A-006



T101550A-007

Suggested PCB Layout

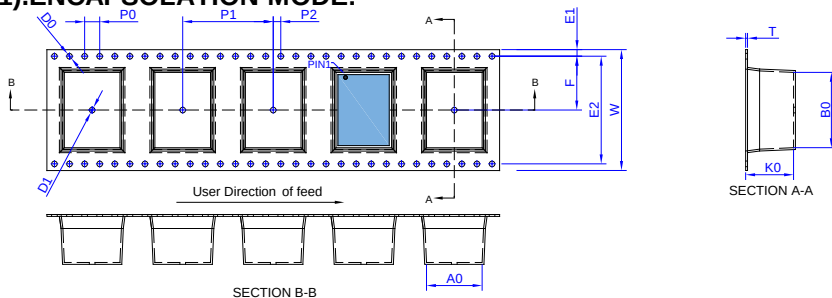
● New York 1 914 347 2474 ● Taipei 886 2 2698 8669 ● Kaohsiung 886 7 350 2275
● Japan 81 568 85 2830 ● Shenzhen 86 755 8418 6263 ● Shanghai 86 21 5424 5141 ● Hong Kong 852 9688 9767

● sales@ITG-Electronics.com ● www.ITG-Electronics.com Revision A.0 : Feb 26, 2025

*Due to continuous product improvement, all specifications are subject to change without prior notice. Kindly contact an ITG field application engineer or a sales representative prior to purchase.

1.PACKAGE SPECIFICATION.(UNIT:mm):

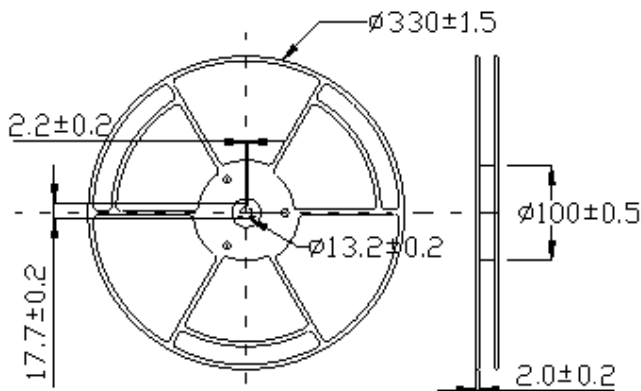
(1).ENCAPSULATION MODE:



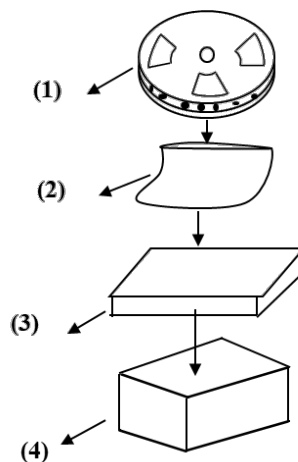
(2).DIMENSION(mm):

W	A0	B0	K0	D0	D1	T	P0	P1	P2	E1	E2	F
44.0±0.3	25.8±0.1	25.6±0.1	9.3±0.1	1.5+0.1/-0.0	1.5+0.1/-0.0	0.5±0.05	4.0±0.1	36.0±0.2	2.0±0.1	1.75±0.1	40.5±0.2	18.5±0.1

(3).REEL SIZE:



(4).PACKAGE MODE:



(5).PACKAGING LIST:

No.	Packing Part	Dimension (mm)	Material	Quantity
1	Reel	330	Plastic	200Pcs/Reel
2	Bag	450x360x0.075	Plastic	1Reel/Bag
3	Small Box	340X335X65	Paper	1Bag/Small Box
4	Outer Box	356X350X226	Paper	3Small Boxes/Outer Box

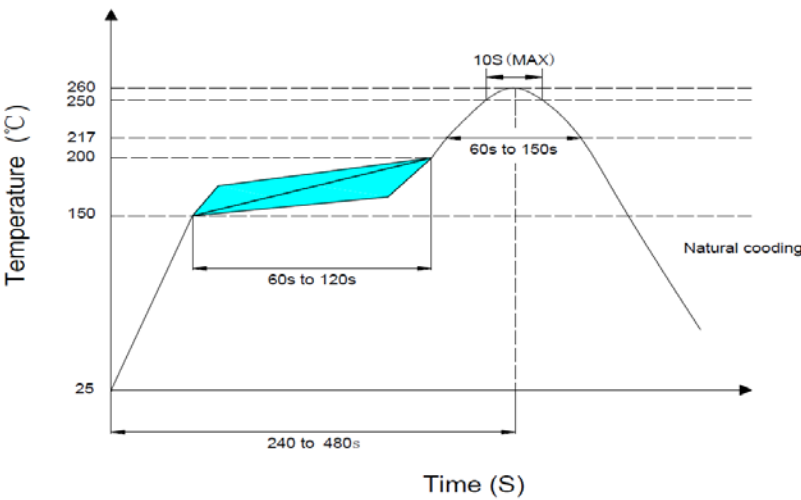
(6).WEIGHT: N.W: 15.80g/pcs TOTAL 9.48Kg(APPROX),G.W:TOTAL 15.08Kg (APPROX).

(7).Storage conditions: -10°C~40°C, 70%RH (Max.).

1.RELIABILITY TEST:

TEST ITEMS	SPECIFICATIONS	TEST METHOD AND REMARKS
Solderability	The electrodes shall be at least 95% covered with new solder coating	According to IEC68-2-20 Method T(Tb) 1. Soldering temperature:260±5℃ 2. Solder: 99.3%Sn/0.7%Cu 3. Flux:Rosin 4. Immersion time:5±1Sec
Resistance to solder heat	1. Appearance : no damage 2. Inductance change:within±10%of initial value	According to MIL-STD-202Method210 1. Preheat temperature150℃ 2. Preheat time:1min 3. Solder temperature260±5℃ 4. Dipping time:10±1Sec 5. Measured at room temperature after placing for 24hours
Vibration(OUT LAB)	1. Appearance : no damage 2. All Electrical and mechanical parameters within tolerance	According to MIL-STD-202G Method 201A 1.Frequency:10 to55Hz 2.Amplitude:1.55mm 3.Direction and timeX Y and Z Direction for 2 hours each (total 6 hours)
Humidity resistance	1. Appearance : no damage 2. All Electrical and mechanical parameters within tolerance	According to IEC68-2-3 Method Ca 1. Temp:40±2℃ 2. Humidity:93 +2/-3%RH 3. Test time:500±2H 4. The component should be stabilized at normal condition for24 Hours before test
High temperature resistance	1. Appearance : no damage 2. All Electrical and mechanical parameters within tolerance	According to IEC68-2-2 Method B(Bd) 1. Temperature:85±3℃ 2. Test time:500+24H/-0H 3. The component should be stabilized at normal condition for 24hours before test
Low Temperature resistance	1. Appearance : no damage 2. All Electrical and mechanical parameters within tolerance	According to IEC68-2-1 Method A(Ad); 1. Temperature:-40±3℃ 2. Test time:500+24H/-0H 3. The component should be stabilized at normal condition for 24hours before test
Temperature cycles	1. Appearance : no damage 2. All Electrical and mechanical parameters within tolerance	According to IEC68-2-14 Method N(Nb); 1. Low-temp:-40±3℃ duration 30min 2. room -temp:25±2℃ duration 3H 3. High-temp:85±3℃ duration 30min 4. room-temp:25±2℃ duration3H 5. Number of cycle:10 cycles 6. The component should be stabilized at normal condition for 24hours before test

Soldering Reflow Chart

Stage	Precaution	Recommended temperature profile
Reflow soldering	Temperature profile can be referenced after confirming of adhesion , temperature of resistance to soldering heat , component size , soldering etc. sufficient . Note: please refer to the latest IPC/JEDEC J-STD-020: "Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices"	 The graph illustrates the recommended temperature profile for reflow soldering. The y-axis represents Temperature in degrees Celsius (°C), ranging from 25 to 260. The x-axis represents Time in seconds (S), ranging from 0 to 480. The profile starts at 25°C, ramps up to 150°C (60s to 120s), then to 200°C (60s to 150s), peaks at 250°C (10s MAX), and finally cools down (Natural cooling). Key temperature points marked are 25, 150, 200, 217, 250, and 260°C.